

Page 17, line 15, change "photo optical quality material" to material that

Q2 facilitates optical interconnection between semiconductor device 16 and an optical wave guide, another semiconductor device, or any source of an optical signal.*--.

line 15, change "billed" to --filled--.

Page 18, line 1, change "Ti/CuT" to --Ti/Cu/Ti--.

Page 19, line 7, change "metal 18" to --thin film overlay 18--.

In the claims:

Amend claim 1 as follows:

1. (Amended) A device comprising:

a package having a cavity therein;

a semiconductor device in said cavity, said semiconductor device having at least one optical receiver and/or transmitter adjacent a surface of said semiconductor device facing away from said package; and

a thin overlay electrically connecting bond pads on said semiconductor device to electrically conductive pads on a layer of said thin film overlay facing away from said semiconductor device.

Amend claim 3 as follows:

Q4 3. (Amended) The device of Claim 2, in which the dimensions of said [package includes a] cavity [that] match[es] or exceed[s] the dimensions of the semiconductor device.

Cancel claims 26 to 44.